

MITSUBISHI IGBT MODULES
CM200DU-24NFH

HIGH POWER SWITCHING USE

CM200DU-24NFH



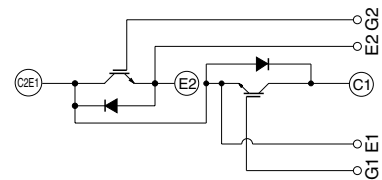
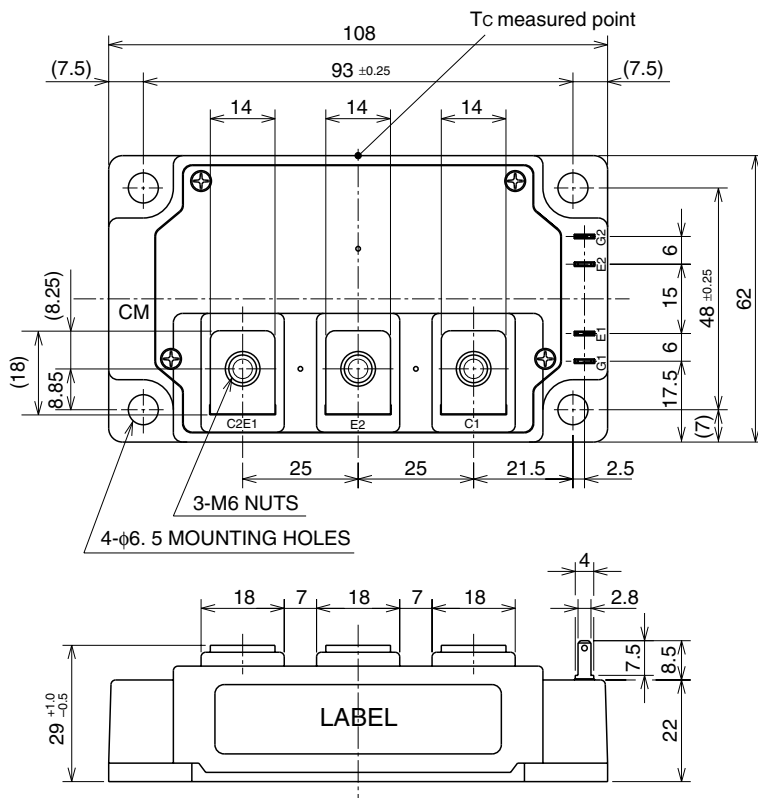
- IC200A
- VCES 1200V
- Insulated Type
- 2-elements in a pack

APPLICATION

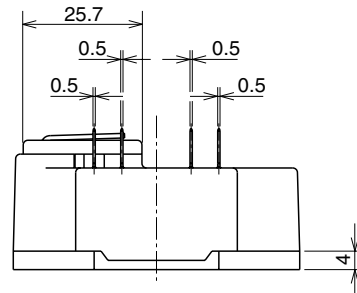
High frequency switching use (30kHz to 60kHz).
 Gradient amplifier, Induction heating, power supply, etc.

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



CIRCUIT DIAGRAM



CM200DU-24NFH

HIGH POWER SWITCHING USE

MAXIMUM RATINGS (Tj = 25°C, unless otherwise specified)

| Symbol | Parameter | Conditions | Ratings | Unit |
|--------------|-------------------------------|--|------------|-------|
| VCES | Collector-emitter voltage | G-E Short | 1200 | V |
| VGES | Gate-emitter voltage | C-E Short | ±20 | V |
| IC | Collector current | Operation (Note 2) | 200 | A |
| ICM | | Pulse (Note 2) | 400 | A |
| IE (Note 1) | Emitter current | Operation (Note 2) | 200 | A |
| IEM (Note 1) | | Pulse (Note 2) | 400 | A |
| PC (Note 3) | Maximum collector dissipation | Tc = 25°C | 830 | W |
| PC' (Note 3) | Maximum collector dissipation | Tc' = 25°C ⁴ | 1300 | W |
| Tj | Junction temperature | | -40 ~ +150 | °C |
| Tstg | Storage temperature | | -40 ~ +125 | °C |
| Viso | Isolation voltage | Terminals to base plate, f = 60Hz, AC 1 minute | 2500 | Vrms |
| — | Mounting torque | Main terminals M6 screw | 3.5 ~ 4.5 | N • m |
| — | | Mounting M6 screw | 3.5 ~ 4.5 | N • m |
| — | Weight | Typical value | 400 | g |

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise specified)

| Symbol | Parameter | Test conditions | Limits | | | Unit |
|--------------|--------------------------------------|--|-----------|------|---------------------|------|
| | | | Min. | Typ. | Max. | |
| ICES | Collector cutoff current | VCE = VCES, VGE = 0V | — | — | 1 | mA |
| VGE(th) | Gate-emitter threshold voltage | IC = 20mA, VCE = 10V | 4.5 | 6 | 7.5 | V |
| IGES | Gate leakage current | ±VGE = VGES, VCE = 0V | — | — | 0.7 | µA |
| VCE(sat) | Collector-emitter saturation voltage | IC = 200A, VGE = 15V | | | | V |
| | | Tj = 25°C | — | 5.0 | 6.5 | |
| | | Tj = 125°C | — | 5.0 | — | |
| Cies | Input capacitance | VCE = 10V VGE = 0V | — | — | 32 | nF |
| Coes | Output capacitance | | — | — | 2.7 | nF |
| Cres | Reverse transfer capacitance | | — | — | 0.6 | nF |
| QG | Total gate charge | VCC = 600V, IC = 200A, VGE = 15V | — | 900 | — | nC |
| td(on) | Turn-on delay time | VCC = 600V, IC = 200A VGE = ±15V RG = 1.6Ω, Inductive load | — | — | 300 | ns |
| tr | Turn-on rise time | | — | — | 80 | ns |
| td(off) | Turn-off delay time | | — | — | 500 | ns |
| tf | Turn-off fall time | | — | — | 150 | ns |
| trr (Note 1) | Reverse recovery time | | IE = 200A | — | — | 250 |
| Qrr (Note 1) | Reverse recovery charge | | — | 7.5 | — | µC |
| VEC(Note 1) | Emitter-collector voltage | IE = 200A, VGE = 0V | — | — | 3.5 | V |
| Rth(j-c)Q | Thermal resistance*1 | IGBT part (1/2 module) | — | — | 0.15 | K/W |
| Rth(j-c)R | | FWDi part (1/2 module) | — | — | 0.24 | K/W |
| Rth(c-f) | Contact thermal resistance | Case to heat sink, Thermal compound Applied*2 (1/2 module) | — | 0.04 | — | K/W |
| Rth(j-c)Q | Thermal resistance*4 | IGBT part (1/2 module) | — | — | 0.095 ^{*3} | K/W |
| Rth(j-c)R | | FWDi part (1/2 module) | — | — | 0.14 ^{*3} | K/W |
| RG | External gate resistance | | 1.6 | — | 16 | Ω |

*1 : Case temperature (Tc) measured point is shown in page OUTLINE DRAWING.

*2 : Typical value is measured by using thermally conductive grease of λ = 0.9[W/(m • K)].

*3 : If you use this value, Rth(f-a) should be measured just under the chips.

*4 : Case temperature (Tc) measured point is just under the chips.

Note 1. IE, IEM, VEC, trr & Qrr represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).

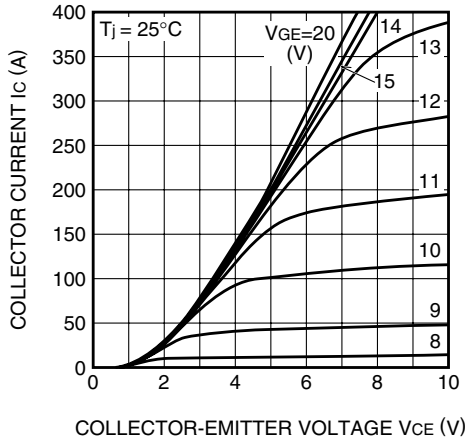
2. Pulse width and repetition rate should be such that the device junction temperature (Tj) does not exceed Tjmax rating.

3. Junction temperature (Tj) should not increase beyond 150°C.

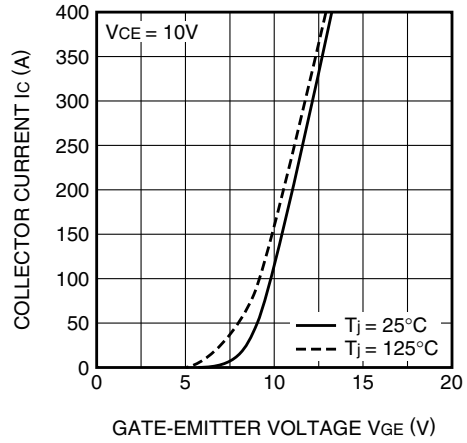
4. No short circuit capability is designed.

PERFORMANCE CURVES

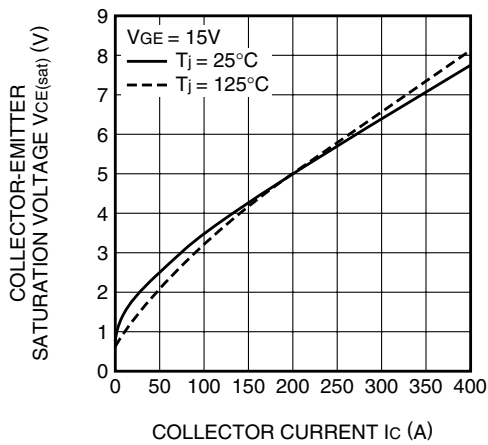
OUTPUT CHARACTERISTICS (TYPICAL)



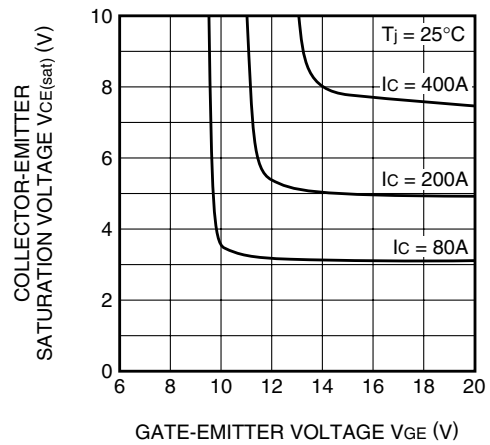
TRANSFER CHARACTERISTICS (TYPICAL)



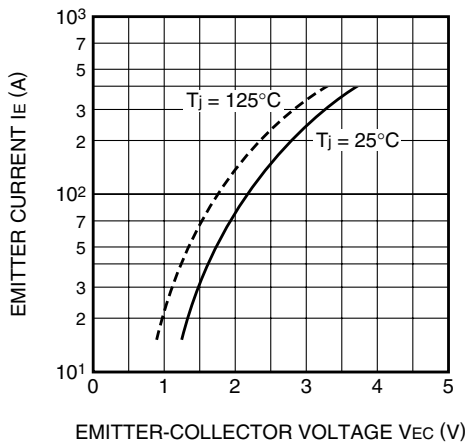
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



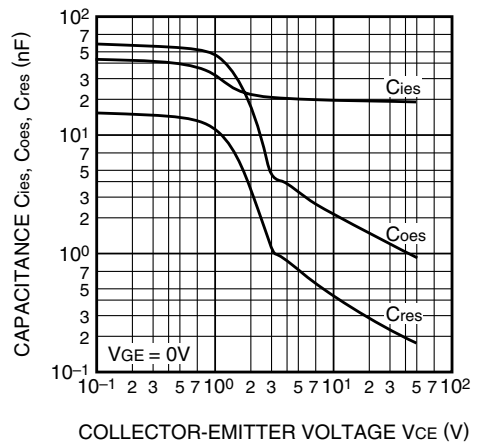
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



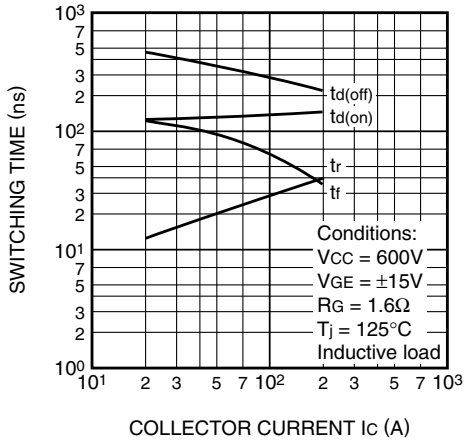
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



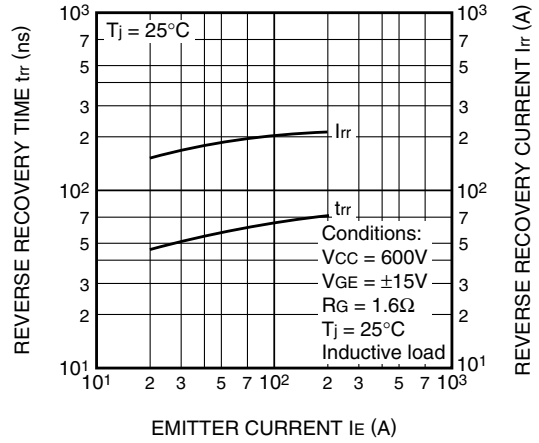
CAPACITANCE CHARACTERISTICS (TYPICAL)



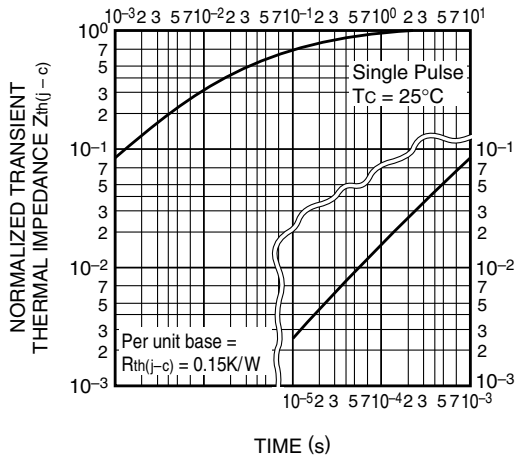
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



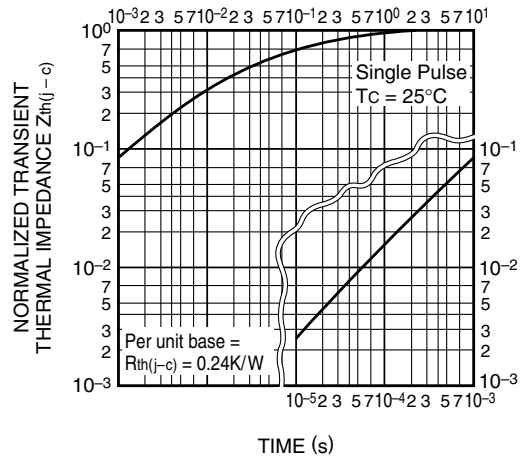
REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (FWDi part)



GATE CHARGE CHARACTERISTICS (TYPICAL)

